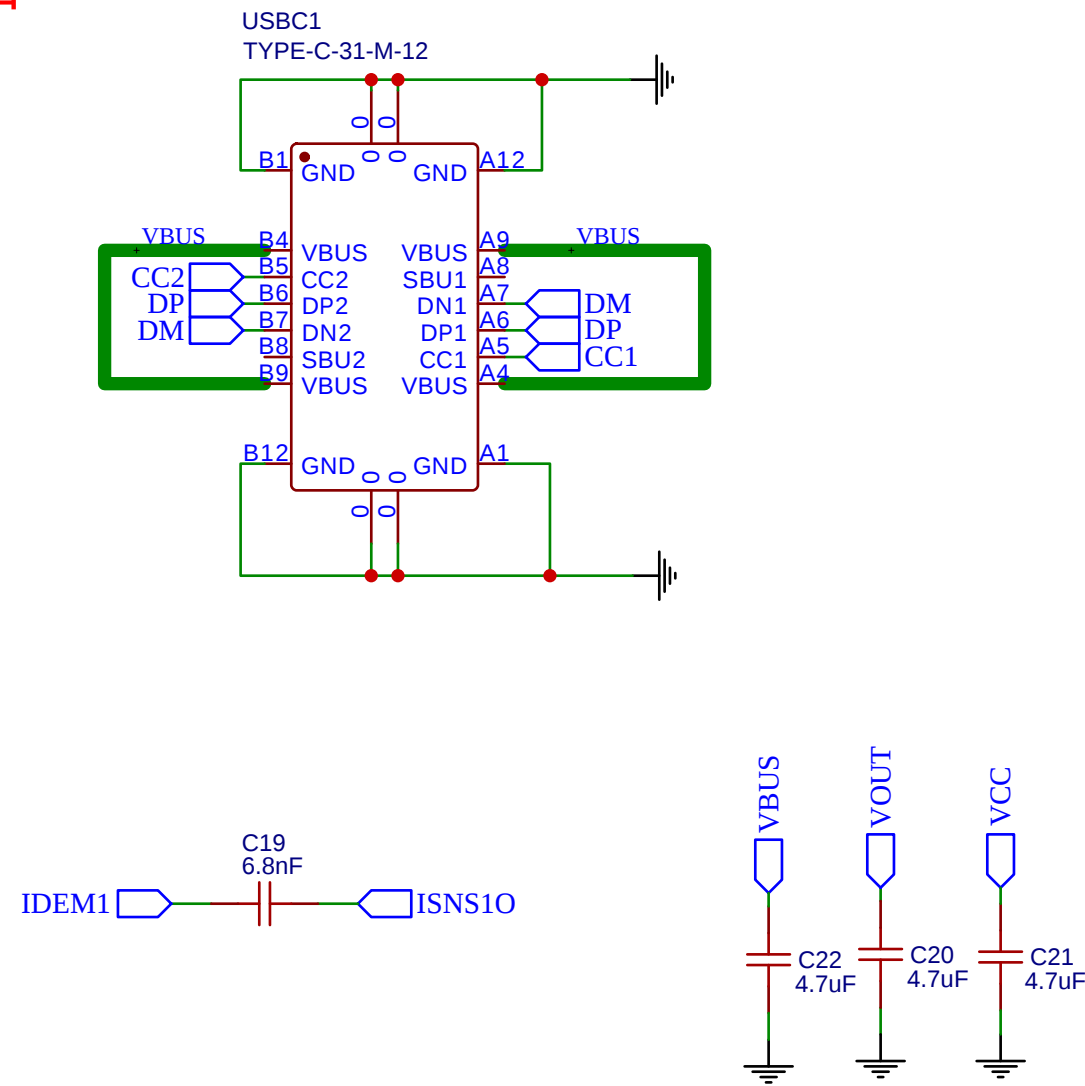
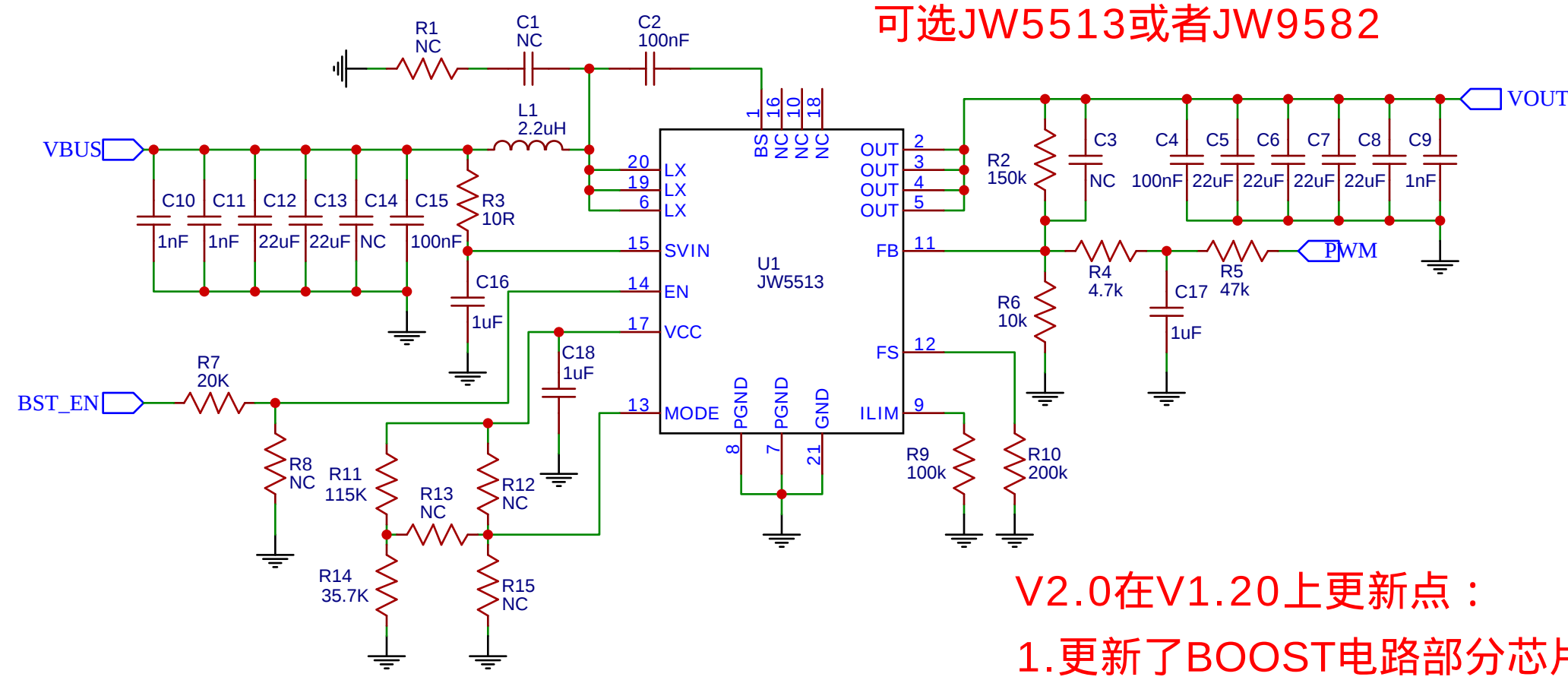


如果没C口，需要加VBUS、DP、DM、GND焊盘接口用于升级
输入接口



输入小电容靠近IC放置

升压芯片

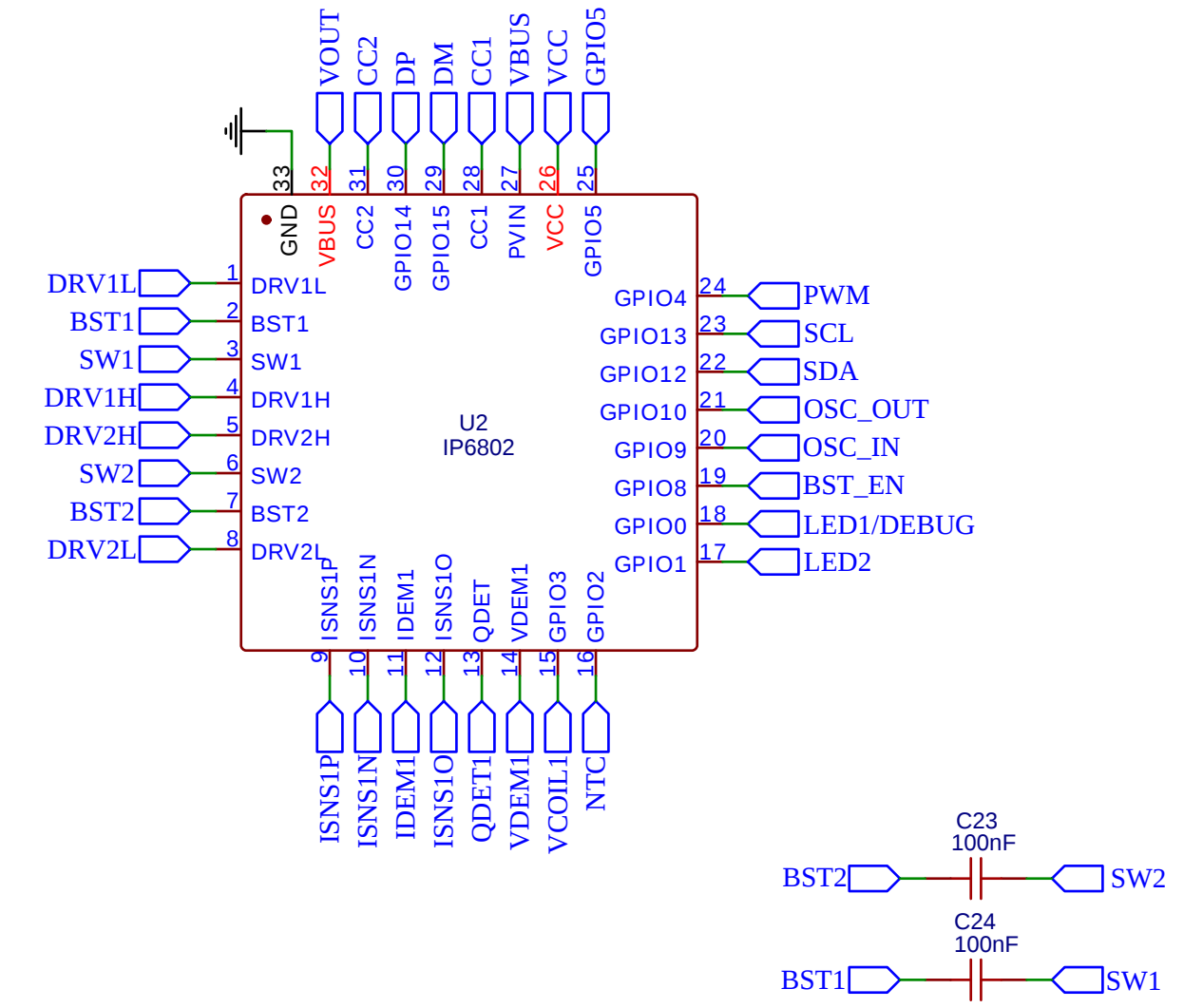


V2.0在V1.20上更新点：

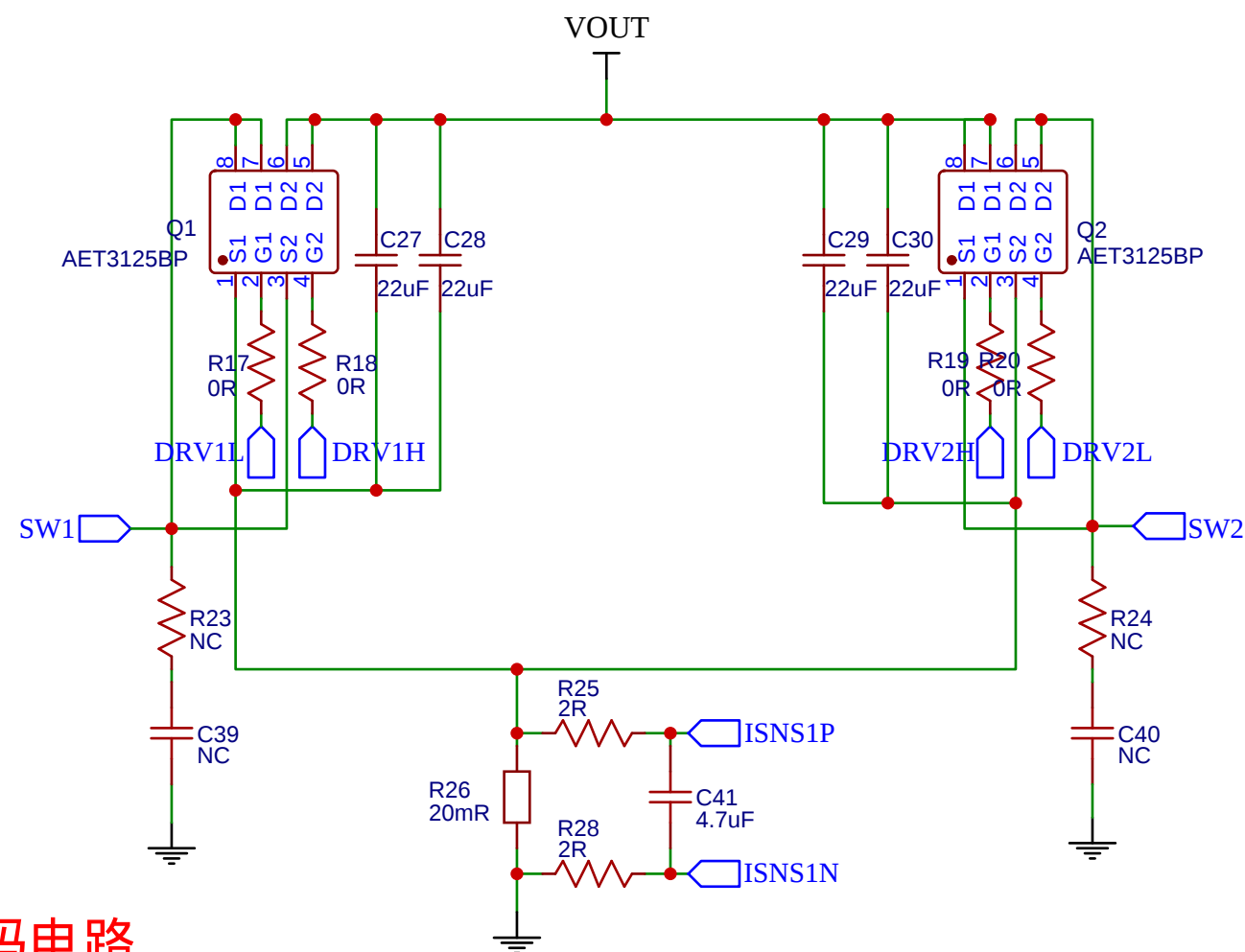
- 1.更新了BOOST电路部分芯片选型
- 2.更新FM1210引脚布局
- 3.外部无源晶振必须要加
- 4.C37改为预留焊盘，删除ISNS10用于调试的电容电阻

主控芯片

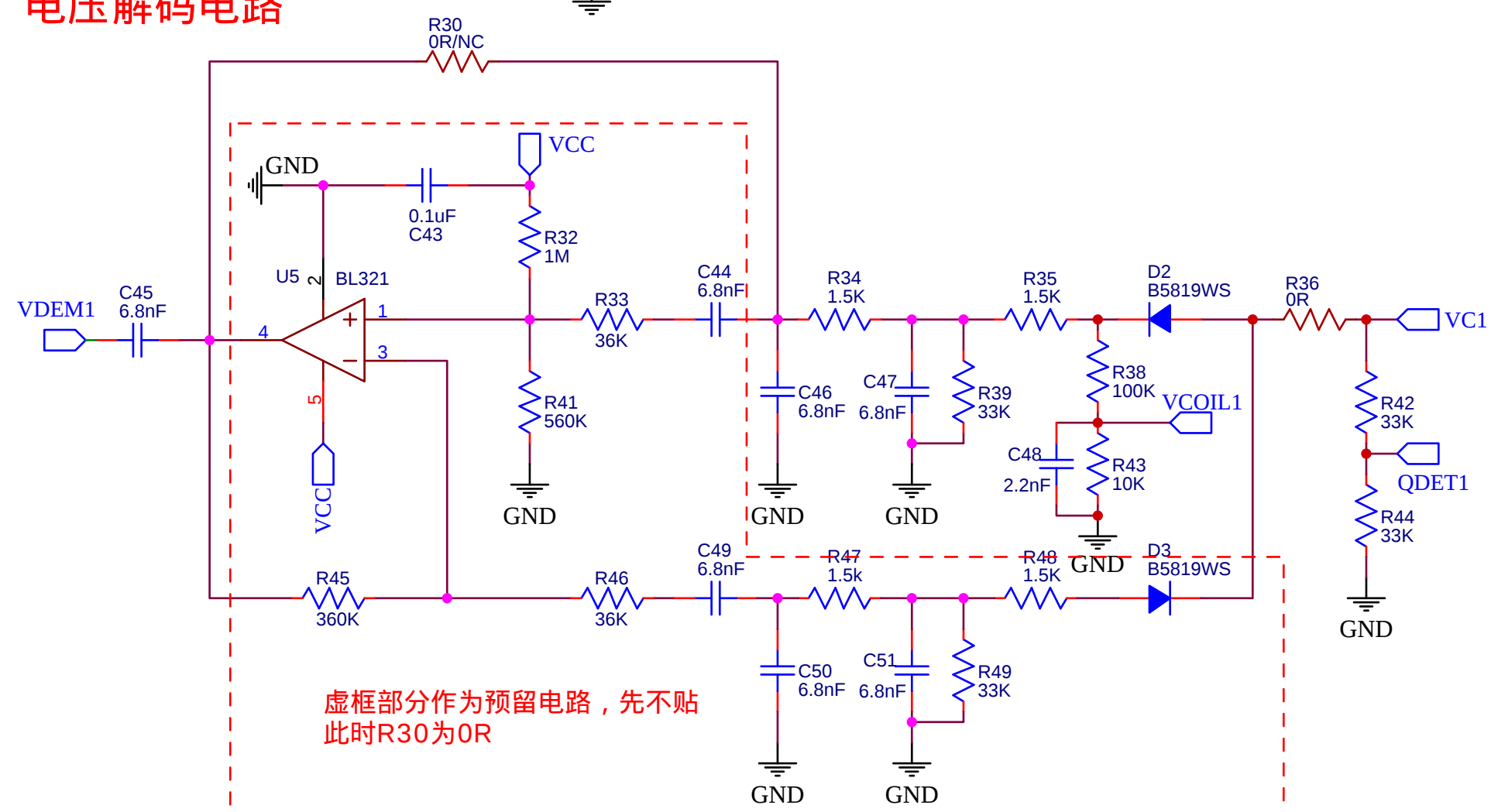
VBUS和VOUT分别采样



H桥控制电路



电压解码电路

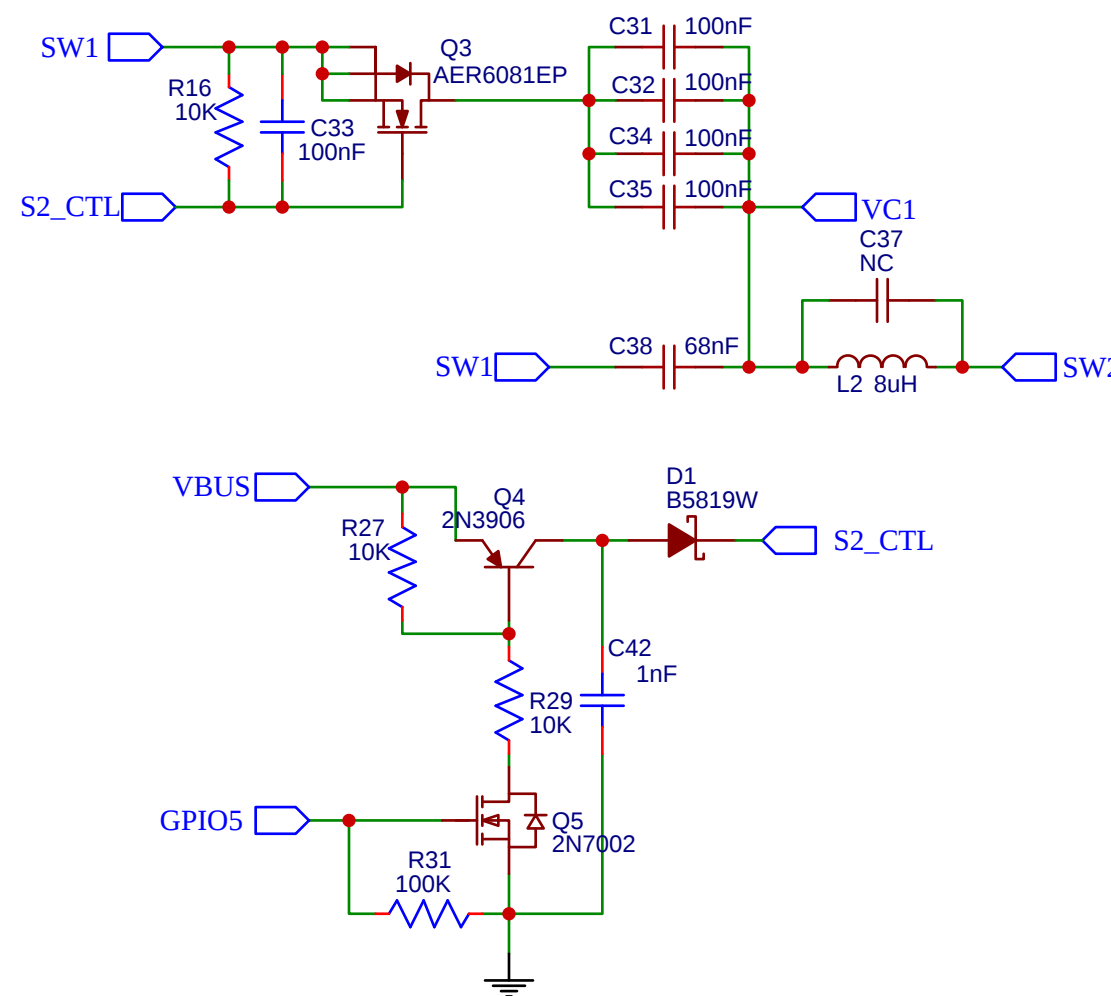


虚框部分作为预留电路，先不贴
此时R30为0R

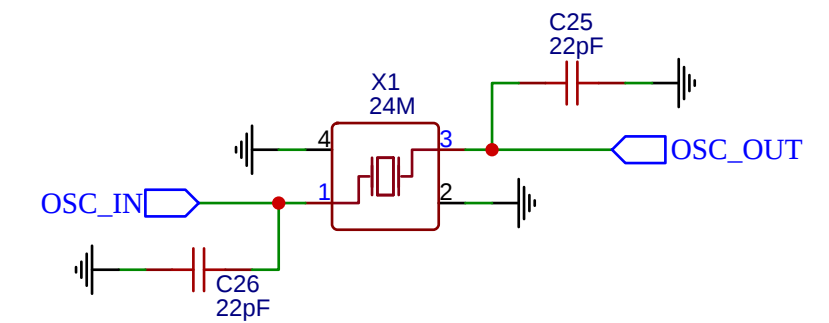
MPP切换电路

- 1、路径切换MOS(Q3)需用60V以上耐压MOS
- 2、线圈表面到外壳表面距离需要在0.9mm-1.1mm之间

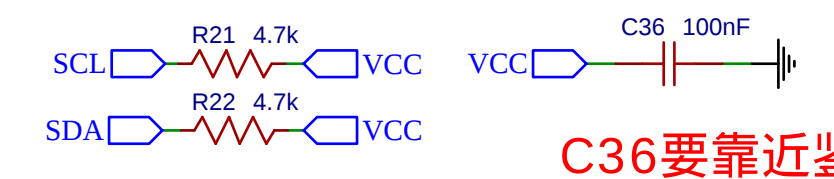
待机使用468nF
进入MPP协议后切换到68nF
搭配8uH感量的能通过MPP线圈测试的磁吸线圈



24M 无源晶振

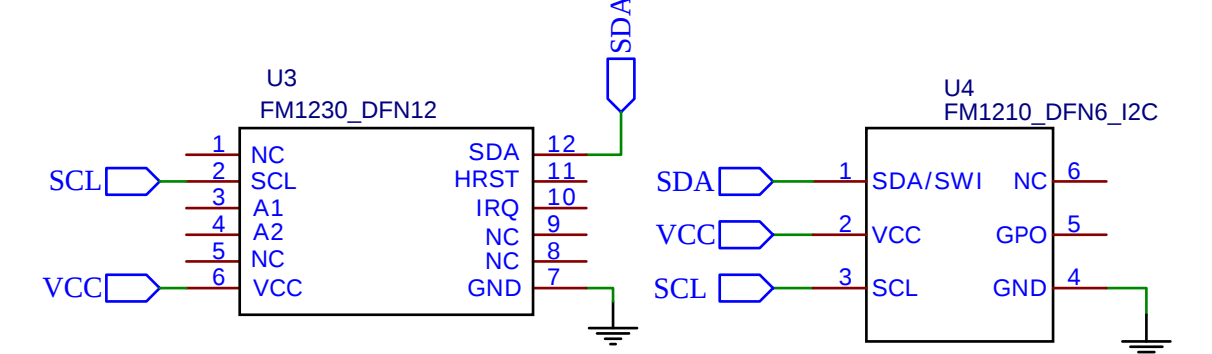


QI2.0加密IC 四选一

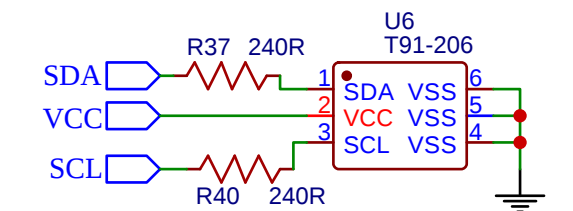


C36要靠近鉴权IC放置

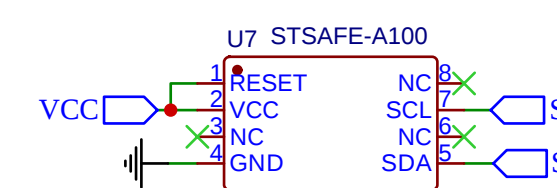
复旦微加密IC



紫光同芯加密IC



ST加密IC



TITLE: IP6802B_MPP_DEMO_V2.0		REV: 2.0
	Company: Injoinic	Sheet: 1/1
	Date: 2024-11-29	Drawn By: IT808